



SURFACE MOUNT SWITCHING DIODE

Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- High Conductance
- Ultra Miniature Package
- Lead Free/RoHS Compliant (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- "Green" Device (Notes 4 and 5)

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.006 grams (approximate)

SOT-363







Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Non-Repetitive Peak Reverse Voltage		V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _R wm	75	V
RMS Reverse Voltage		V _{R(RMS)}	53	V
Forward Continuous Current	(Note 1)	I _{FM}	500	mA
Average Rectified Output Current	(Note 1)	lo	250	mA
Non-Repetitive Peak Forward Surge Current	@ t < 1μs @ t < 1s	I _{FSM}	4 2	А

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 1)	P_{D}	200	mW
Thermal Resistance Junction to Ambient Air	(Note 1)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage	(Note 2)	V _{(BR)R}	75	_	V	$I_R = 10\mu A$
			0.62	0.720		$I_F = 5.0 \text{mA}$
Forward Voltage		V _F	_	0.855	V	$I_F = 10 \text{mA}$
l olward voltage			_	1.0		$I_F = 50 \text{mA}$
				1.25		I _F = 150mA
				2.5	μΑ	$V_R = 75V$
Reverse Current	(Note 2)	I _R	_	50	μΑ	$V_R = 75V, T_J = 150$ °C
Neverse Current				30	μΑ	$V_R = 25V, T_J = 150$ °C
				25	nA	$V_R = 20V$
Total Capacitance		C _T	_	4.0	pF	$V_R = 0, f = 1.0MHz$
Reverse Recovery Time		t _{rr}		4.0	ns	$I_F = I_R = 10 \text{mA},$
Neverse Necovery Time						$I_{rr} = 0.1 \text{ x } I_{R}, R_{L} = 100\Omega$

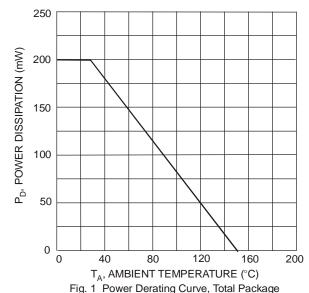
Notes:

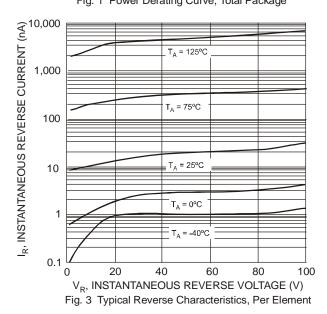
- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- Short duration pulse test used to minimize self-heating.
- No purposefully added lead.
- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

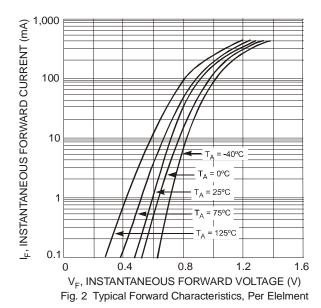
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MMBD4448DW









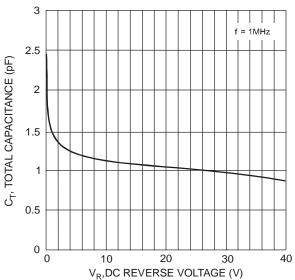


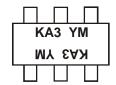
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Ordering Information (Note 6)

Part Number	Case	Packaging
MMBD4448DW-7-F	SOT-363	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



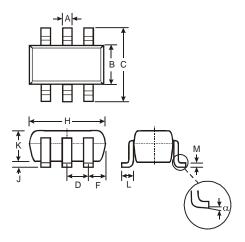
KA3 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: N = 2002) M = Month (ex: 9 = September)

Date Code Key

Date Code Hoy													
Year	2000	2001	2002	2003	2004	2005	2006	200	7 200	8 2009	2010	2011	2012
Code	L	М	N	Р	R	S	Т	U	V	W	Х	Υ	Z
Month	Jan	Feb	Mar	Apr	Ma	y J	un	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5		6	7	8	9	0	Ν	D

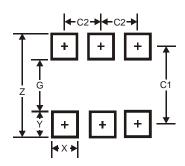


Package Outline Dimensions



	SOT-363					
Dim	Min	Max				
Α	0.10	0.30				
В	1.15	1.35				
С	2.00	2.20				
D	0.65 Typ					
F	0.40	0.45				
Н	1.80	2.20				
J	0	0.10				
K	0.90	1.00				
L	0.25 0.40					
M	0.10	0.22				
α	0°	8°				
All Di	All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65

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